

Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model [List multiple models if applicable.]

HP Compaq 8000 Elite Ultra Slim Desktop Business PC

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

- 1.1 Items listed below are classified as requiring selective treatment.
- 1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm system board, adaptor	2
Batteries	All types including standard alkaline and lithium coin or button style batteries system board	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	adaptor	1
External electrical cables and cords	adaptor	1
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0

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Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers	adaptor	4
Components, parts and materials containing radioactive substances		0

1.3 Markings for plastic parts greater than 25 grams

Plastic Part Name	Plastic Part Description	Weight (grams)	ISO 11469:2000 Plastic Part Mark	Optional: Photo
Bezel	Front bezel of USDT	51.9g	>ABS<	
fan duct	Front fan duct	29.35g	>PC+ABS FR(40)<	
Stand	USDT stand	94.20g	>ABS<	
port cover	rear cable cover	146.6g	>PC+ABS FR(40)<	

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Phillips Slotted Screwdriver	
Phillips Cross Screwdriver	
Diagonal cutting plier (for Adaptor only)	
Needle nose pliers (for Adaptor only)	
Description #5	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

[System]

- 1. Remove top cover
- 2. Remove button cell (requiring selective treatment)
- 3. Remove front bezel
- 4. Remove ODD cable and ODD
- 5. Remove HDD module
- 6. Remove ODD/HDD bracket
- 7. Remove front I/O cage
- 8. Remove CPU fan
- 9. Remove heat sink
- 10. Remove system board (> 10 cm2 requiring selective treatment)

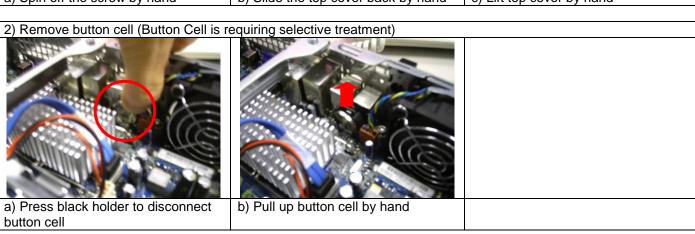
[Adaptor]

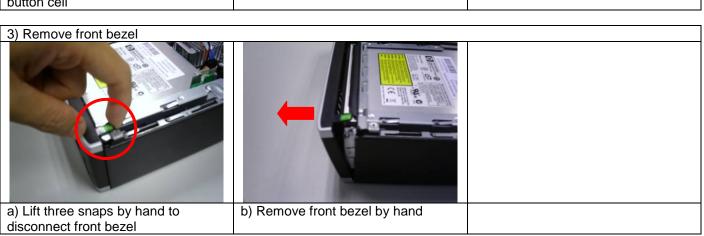
- 1. Remove covers
- 2. Remove aluminum shielding
- 3. Remove sheet metal shielding
- 4. Remove capacitor (>2.5 cm in height, requiring selective treatment)
- 5. Remove external cable (requiring selective treatment)
- 6. Remove components containing ceramic fibers (requiring selective treatment)
- 7. Left adaptor printed wiring board (>10 cm2, requiring selective treatment)

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations)

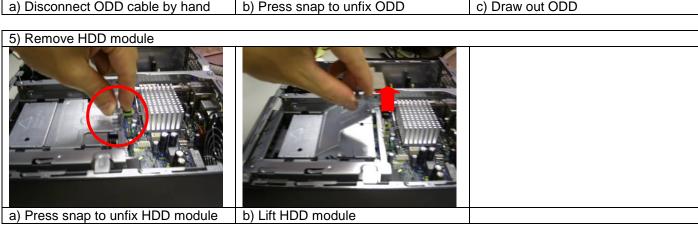
[System]

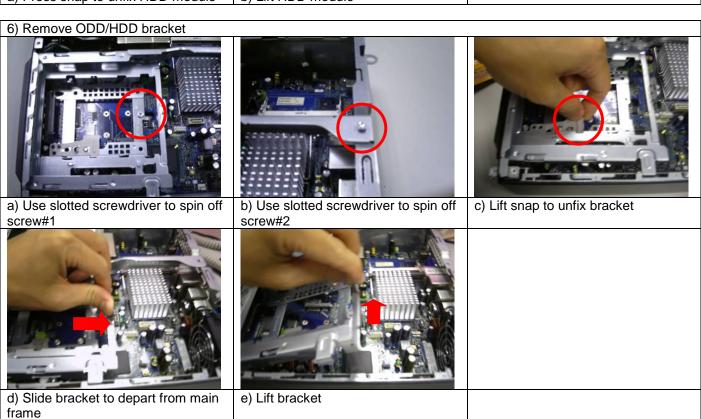






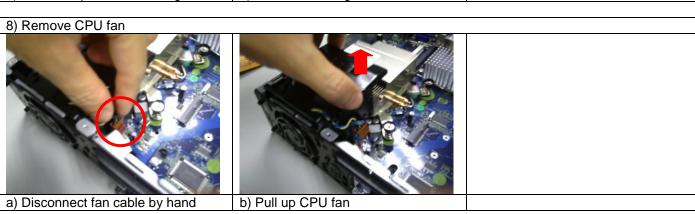


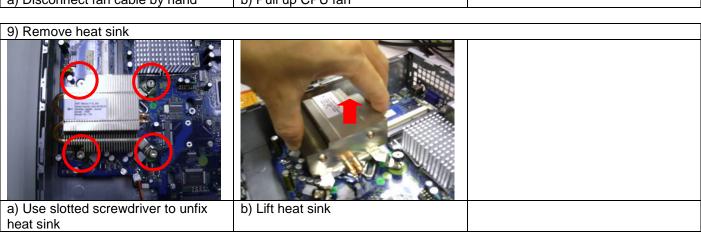


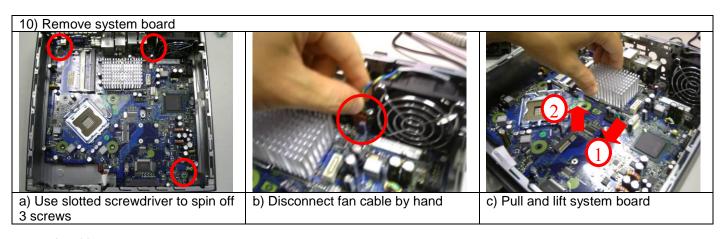


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[Adaptor]

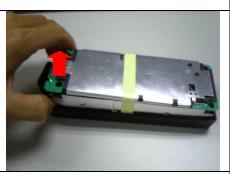
1) Remove covers



a) Use cross screwdriver to spin off four screws



b) Remove top cover by hand



c) Remove bottom cover by hand





a) Tear down electrical tape by hand



b) Remove bottom aluminum shielding

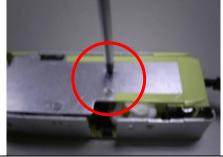


c) Use diagonal cutting plier to disconnect top aluminum shielding

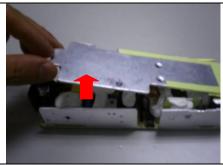
3) Remove sheet metal shielding



a) Tear down tinfoil



b) Use cross screwdriver to spin off two screws



c) Lift sheet metal shielding

4) Remove capacitor (>2.5cm in height)				
a) Use diagonal cutting plier to disconnect capacitor (> 2.5cm in height)				

